



Material Content Data Sheet



Halogen-Free

Sales Product Name	TDA38640-0000	Issued	18. May 2022
MA#	MA005593509		
Package	PG-IQFN-36-3	Weight*	119.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.200	0.17	0.17	1675	1675
chip_2	inorganic material	silicon	7440-21-3	0.690	0.58	0.58	5794	5794
chip_3	inorganic material	silicon	7440-21-3	3.369	2.83	2.83	28289	28289
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	zinc	7440-66-6	0.044	0.04		371	
	non noble metal	iron	7439-89-6	0.884	0.74		7426	
	non noble metal	copper	7440-50-8	35.912	30.15	30.94	301508	309398
wire	noble metal	gold	7440-57-5	0.341	0.29	0.29	2861	2861
encapsulation	organic material	carbon black	1333-86-4	0.325	0.27		2731	
	non noble metal	metal hydroxide	-	0.651	0.55		5462	
	inorganic material	amorphous silica	7631-86-9	2.277	1.91		19118	
	plastics	epoxy resin	-	3.253	2.73		27311	
	inorganic material	silicondioxide	60676-86-0	26.024	21.85	27.31	218486	273108
leadfinish	noble metal	palladium	7440-05-3	0.003			26	
	noble metal	gold	7440-57-5	0.005			42	
	non noble metal	nickel	7440-02-0	0.091	0.08	0.08	763	831
plating	noble metal	silver	7440-22-4	0.755	0.63	0.63	6339	6339
solder	noble metal	silver	7440-22-4	0.120	0.10		1009	
	non noble metal	tin	7440-31-5	0.240	0.20		2019	
	non noble metal	lead	7439-92-1	4.449	3.74	4.04	37350	40378
heat sink clip	inorganic material	phosphorus	7723-14-0	0.012	0.01		99	
	non noble metal	zinc	7440-66-6	0.047	0.04		398	
	non noble metal	iron	7439-89-6	0.947	0.80		7952	
	non noble metal	copper	7440-50-8	38.458	32.28	33.13	322878	331327
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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